

2SJ479(L), 2SJ479(S)

Silicon P Channel MOS FET

REJ03G0866-0300 Rev.3.00 Jun 05, 2006

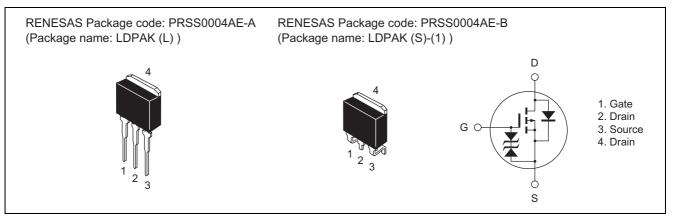
Description

High speed power switching

Features

- Low on-resistance
- $R_{DS(on)} = 25 \text{ m}\Omega \text{ typ.}$
- 4 V gate drive devices.
- High speed switching

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-30	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	-30	А
Drain peak current	I _{D (pulse)} Note 1	-120	A
Body to drain diode reverse drain current	I _{DR}	-30	A
Channel dissipation	Pch Note 2	50	W
Channel temperature	Tch	150	۵°
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. Value at Tc = $25^{\circ}C$

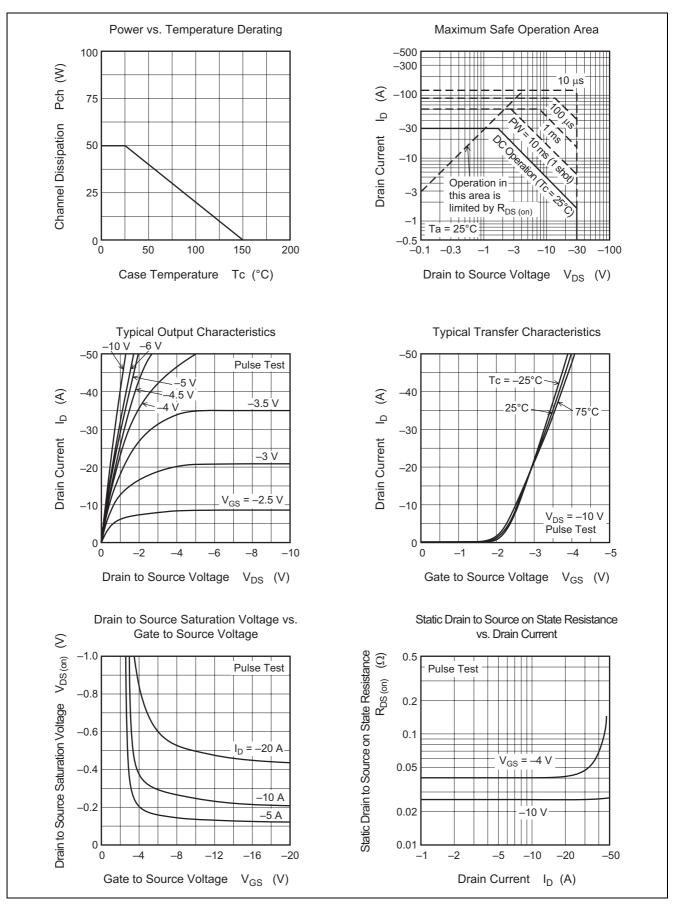
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-30	_	—	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20	_	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	_	-10	μA	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	—	_	±10	μA	$V_{GS} = \pm 16 V, V_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	_	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	—	25	35	mΩ	$I_D = -15 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	—	40	60	mΩ	$I_D = -15 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	12	20	—	S	$I_D = -15 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	—	1700	—	pF	$V_{DS} = -10 V$
Output capacitance	Coss	—	950	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	260	—	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	—	20	—	ns	$V_{GS} = -10 \text{ V}$
Rise time	tr	_	290	_	ns	$I_{\rm D} = -15 {\rm A}$
Turn-off delay time	t _{d (off)}	—	170	_	ns	$R_L = 0.67 \ \Omega$
Fall time	t _f	_	130		ns	
Body to drain diode forward voltage	V _{DF}		-1.1	—	V	$I_F = -30 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	70	_	ns	$I_F = -30 \text{ A}, V_{GS} = 0$
						di _F /dt = 50 A/µs

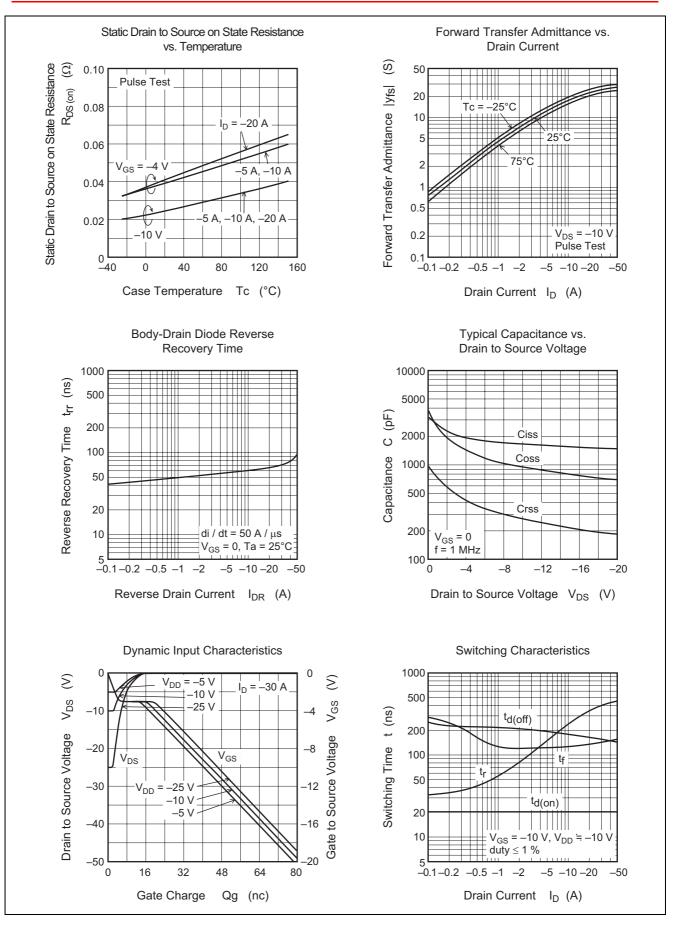
Note: 3. Pulse test



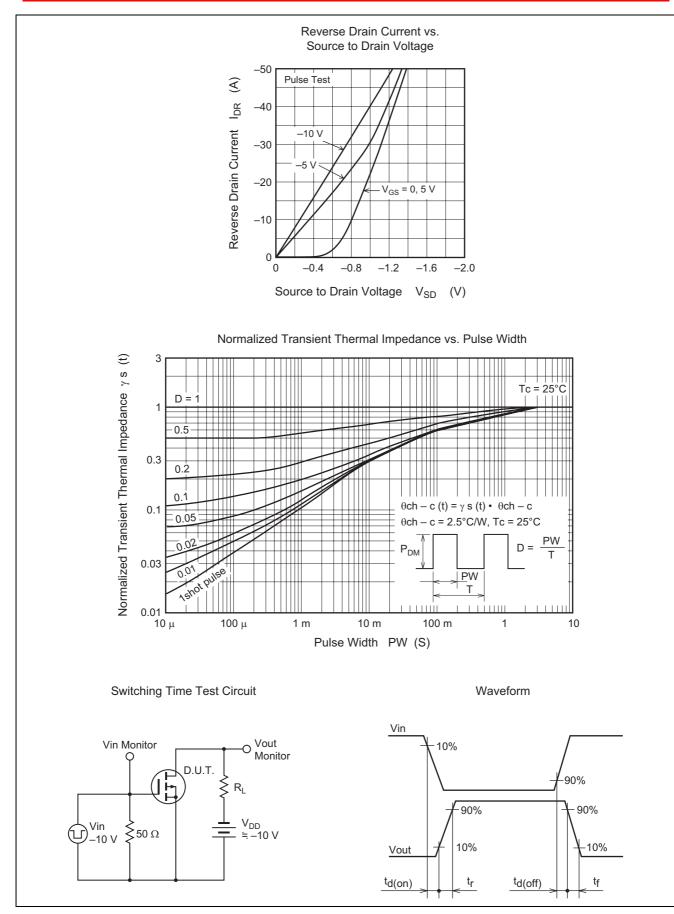
Main Characteristics





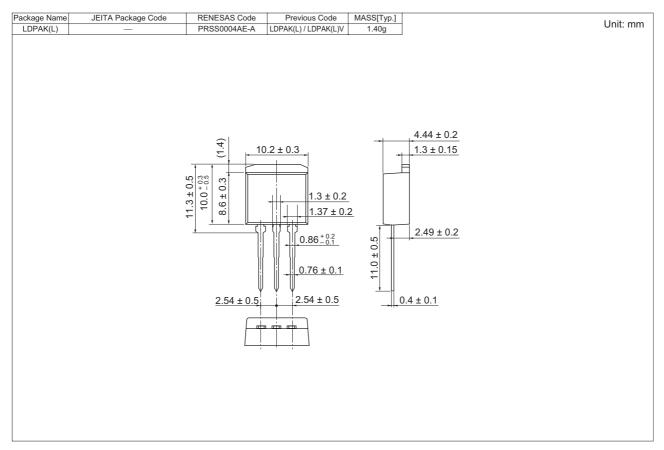


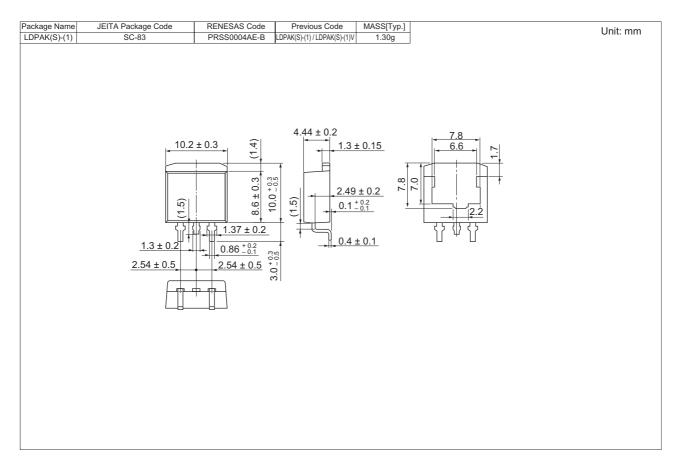






Package Dimensions







Ordering Information

Part Name	Quantity	Shipping Container
2SJ479L-E	500 pcs	Box (Sack)
2SJ479STL-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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